

Gwent Electronic Materials C2030529D2 Silver Via Ink

Category: Fluid, Other Engineering Material, Additive/Filler for Polymer

Material Notes:

This product is based on a unique curing process that results in the low temperature formation of a thermosetting conductive adhesive that combines good adhesion and electrical conductivity with chemical, environmental and abrasion resistance. It offers the advantage of a One-Pak cure system combined with the convenience of Ambient Temperature stability. Application: Through hole or via filling Information provided by Gwent Electronic Materials Ltd.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Gwent-Electronic-Materials-C2030529D2-Silver-Via-Ink.php

Processing Properties	Metric	English	Comments
Cure Time	30.0 min	0.500 hour	
	@Temperature 160 °C	@Temperature 320 °F	

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